

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT4889620

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT	
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT	
<b>CONVEYING PARTY DATA</b>		
	<b>Name</b>	<b>Execution Date</b>
	DEBENDRA DAS SHARMA	07/10/2017
	MICHELLE C. JEN	07/10/2017
	MARK S. MYERS	07/19/2017
	DON SOLTIS	07/27/2017
	RAMACHARAN SUNDARARAMAN	09/05/2017
	STEPHEN R. VAN DOREN	07/13/2017
	MAHESH WAGH	07/10/2017
<b>RECEIVING PARTY DATA</b>		
<b>Name:</b>	INTEL CORPORATION	
<b>Street Address:</b>	2200 MISSION COLLEGE BOULEVARD	
<b>City:</b>	SANTA CLARA	
<b>State/Country:</b>	CALIFORNIA	
<b>Postal Code:</b>	95054	
<b>PROPERTY NUMBERS Total: 1</b>		
	<b>Property Type</b>	<b>Number</b>
	Application Number:	15639393
<b>CORRESPONDENCE DATA</b>		
<b>Fax Number:</b>		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
<b>Phone:</b>	919-595-6508	
<b>Email:</b>	rmoye@kdbfirm.com	
<b>Correspondent Name:</b>	KACVINSKY DAISAK BLUNI PLLC ATTENTION: T	
<b>Address Line 1:</b>	430 DAVIS DRIVE	
<b>Address Line 2:</b>	SUITE 150	
<b>Address Line 4:</b>	MORRISVILLE, NORTH CAROLINA 27560	
<b>ATTORNEY DOCKET NUMBER:</b>	P109712	
<b>NAME OF SUBMITTER:</b>	RODDY MOYE	
<b>SIGNATURE:</b>	/Roddy Moye/	
<b>DATE SIGNED:</b>	03/29/2018	

PATENT

**Total Attachments: 14**

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DEBENDRA DAS SHARMA; MICHELLE C. JEN; MARK S. MYERS; DON SOLTIS; RAMACHARAN  
SUNDARARAMAN; STEPHEN R. VAN DOREN; MAHESH WAGH

hereby sell, assign, and transfer to:

### **Intel Corporation**

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95054 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all other countries, in and to any and all inventions and improvements that are disclosed in the application for the patent entitled:

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COUNTRY or International Office

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Debendra Das Sharma  
DEBENDRA DAS SHARMA

7/10/17  
Date signed

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MICHELLE C. JEN

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Date signed

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MARK S. MYERS

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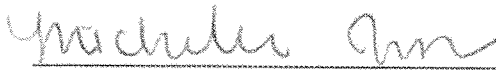
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DEBENDRA DAS SHARMA

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MICHELLE C. JEN

7-10-2017  
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7-19-2017

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7.27.17

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